

## ABSTRACT

A semiconductor package comprising a semiconductor wafer having an active surface comprising at least one integrated circuit, wherein each integrated circuit has a plurality of bond pads; and at least one cured silicone member covering at least a portion of the active surface, wherein at least a portion of each bond pad is not covered by the silicone member, the silicone member has a coefficient of linear thermal expansion of from 60 to 280  $\mu\text{m}/\text{m}^\circ\text{C}$  between -40 and 150  $^\circ\text{C}$  and a modulus of from 1 to 300 MPa at 25  $^\circ\text{C}$ , and the silicone member is prepared by the method of the invention.

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